B-Suffix Series CMOS Gates

MC14001B, MC14011B, MC14023B, MC14025B, MC14071B, MC14073B, MC14081B, MC14082B

The B Series logic gates are constructed with P and N channel enhancement mode devices in a single monolithic structure (Complementary MOS). Their primary use is where low power dissipation and/or high noise immunity is desired.

Features

- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- All Outputs Buffered
- Capable of Driving Two Low-power TTL Loads or One Low-power Schottky TTL Load Over the Rated Temperature Range.
- Double Diode Protection on All Inputs Except: Triple Diode Protection on MC14011B and MC14081B
- Pin-for-Pin Replacements for Corresponding CD4000 Series B Suffix Devices
- Pb-Free Packages are Available*

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Symbol	Parameter	Value	Unit	
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V	
V _{in} , V _{out}	Input or Output Voltage Range (DC or Transient)	-0.5 to V _{DD} + 0.5	V	
I _{in} , I _{out}	Input or Output Current (DC or Transient) per Pin	±10	mA	
P _D	Power Dissipation, per Package (Note 1)	500	mW	
T _A	Ambient Temperature Range	-55 to +125	°C	
T _{stg}	Storage Temperature Range	-65 to +150	°C	
T _L	Lead Temperature (8–Second Soldering)	260	°C	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Temperature Derating:

Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



http://onsemi.com

MARKING DIAGRAMS



PDIP-14 P SUFFIX CASE 646





SOIC-14 D SUFFIX CASE 751A





TSSOP-14 DT SUFFIX CASE 948G





SOEIAJ-14 F SUFFIX CASE 965



xx = Specific Device Code A = Assembly Location WL, L = Wafer Lot

YY, Y = Year
WW, W = Work Week

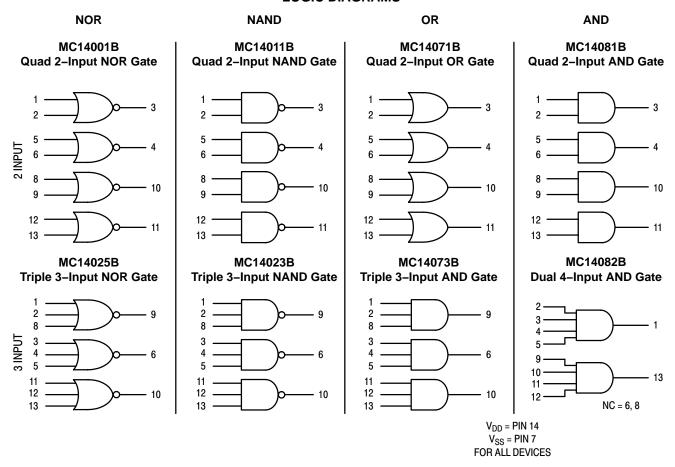
DEVICE INFORMATION

Device	Description
MC14001B	Quad 2-Input NOR Gate
MC14011B	Quad 2-Input NAND Gate
MC14023B	Triple 3-Input NAND Gate
MC14025B	Triple 3-Input NOR Gate
MC14071B	Quad 2-Input OR Gate
MC14073B	Triple 3-Input AND Gate
MC14081B	Quad 2-Input AND Gate
MC14082B	Dual 4-Input AND Gate

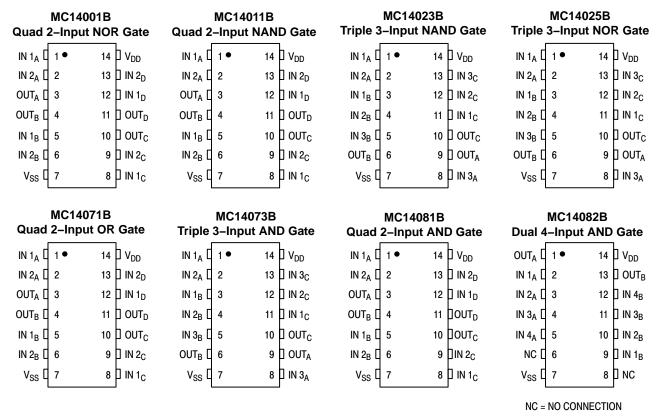
ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

LOGIC DIAGRAMS



PIN ASSIGNMENTS



ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

			V _{DD}	- 55	5°C		25°C		125	5°C	
Characteristic		Symbol	Vdc	Min	Max	Min	Typ ⁽²⁾	Max	Min	Max	Unit
Output Voltage V _{in} = V _{DD} or 0	"0" Level	V _{OL}	5.0 10 15	- - -	0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
V _{in} = 0 or V _{DD}	"1" Level	V _{OH}	5.0 10 15	4.95 9.95 14.95	- - -	4.95 9.95 14.95	5.0 10 15	- - -	4.95 9.95 14.95	- - -	Vdc
Input Voltage $(V_O = 4.5 \text{ or } 0.5 \text{ Vdc})$ $(V_O = 9.0 \text{ or } 1.0 \text{ Vdc})$ $(V_O = 13.5 \text{ or } 1.5 \text{ Vdc})$	"0" Level	V _{IL}	5.0 10 15	- - -	1.5 3.0 4.0	- - -	2.25 4.50 6.75	1.5 3.0 4.0	- - -	1.5 3.0 4.0	Vdc
$(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	"1" Level	V _{IH}	5.0 10 15	3.5 7.0 11	- - -	3.5 7.0 11	2.75 5.50 8.25	- - -	3.5 7.0 11	- - -	Vdc
Output Drive Current $ (V_{OH} = 2.5 \text{ Vdc}) $ $ (V_{OH} = 4.6 \text{ Vdc}) $ $ (V_{OH} = 9.5 \text{ Vdc}) $ $ (V_{OH} = 13.5 \text{ Vdc}) $	Source	I _{OH}	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	- - -	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	- - -	- 1.7 - 0.36 - 0.9 - 2.4	- - -	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	I _{OL}	5.0 10 15	0.64 1.6 4.2	- - -	0.51 1.3 3.4	0.88 2.25 8.8	- - -	0.36 0.9 2.4	- - -	mAdc
Input Current		I _{in}	15	-	± 0.1	_	±0.00001	± 0.1	_	± 1.0	μAdc
Input Capacitance (V _{in} = 0)		C _{in}	-	-	-	_	5.0	7.5	_	-	pF
Quiescent Current (Per Package)		I _{DD}	5.0 10 15	- - -	0.25 0.5 1.0	- - -	0.0005 0.0010 0.0015	0.25 0.5 1.0	- - -	7.5 15 30	μAdc
Total Supply Current (3) (4) (Dynamic plus Quiesce Per Gate, C _L = 50 pF)		I _T	5.0 10 15		1	$I_{T} = (0.$	3 μΑ/kHz) f + 6 μΑ/kHz) f + 9 μΑ/kHz) f +	+ I _{DD} /N	ı	1	μAdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where: I_T is in μA (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and k = 0.001 x the number of exercised gates per package.

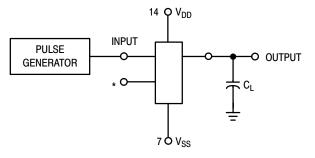
B-SERIES GATE SWITCHING TIMES

SWITCHING CHARACTERISTICS (5) ($C_L = 50 \text{ pF}, T_A = 25^{\circ}\text{C}$)

Characteristic	Symbol	V _{DD} Vdc	Min	Typ ⁽⁶⁾	Max	Unit
Output Rise Time, All B-Series Gates	t _{TLH}					ns
$t_{TLH} = (1.35 \text{ ns/pF}) C_L + 33 \text{ ns}$		5.0	_	100	200	
$t_{TLH} = (0.60 \text{ ns/pF}) C_L + 20 \text{ ns}$		10	_	50	100	
$t_{TLH} = (0.40 \text{ ns/PF}) C_L + 20 \text{ ns}$		15	-	40	80	
Output Fall Time, All B-Series Gates	t _{THL}					ns
$t_{THL} = (1.35 \text{ ns/pF}) C_L + 33 \text{ ns}$		5.0	_	100	200	
$t_{THL} = (0.60 \text{ ns/pF}) C_L + 20 \text{ ns}$		10	_	50	100	
$t_{THL} = (0.40 \text{ ns/pF}) C_L + 20 \text{ ns}$		15	_	40	80	
Propagation Delay Time	t _{PLH} , t _{PHL}					ns
MC14001B, MC14011B only						
t_{PLH} , $t_{PHL} = (0.90 \text{ ns/pF}) C_L + 80 \text{ ns}$		5.0	_	125	250	
t_{PLH} , $t_{PHL} = (0.36 \text{ ns/pF}) C_L + 32 \text{ ns}$		10	_	50	100	
t_{PLH} , $t_{PHL} = (0.26 \text{ ns/pF}) C_L + 27 \text{ ns}$		15	_	40	80	
All Other 2, 3, and 4 Input Gates						
t_{PLH} , $t_{PHL} = (0.90 \text{ ns/pF}) C_L + 115 \text{ ns}$		5.0	_	160	300	
t_{PLH} , $t_{PHL} = (0.36 \text{ ns/pF}) C_L + 47 \text{ ns}$		10	_	65	130	
t_{PLH} , $t_{PHL} = (0.26 \text{ ns/pF}) C_L + 37 \text{ ns}$		15	_	50	100	
8-Input Gates (MC14068B, MC14078B)						
t_{PLH} , $t_{PHL} = (0.90 \text{ ns/pF}) C_L + 155 \text{ ns}$		5.0	_	200	350	
t_{PLH} , $t_{PHL} = (0.36 \text{ ns/pF}) C_L + 62 \text{ ns}$		10	_	80	150	
t_{PLH} , $t_{PHL} = (0.26 \text{ ns/pF}) C_L + 47 \text{ ns}$		15	_	60	110	

^{5.} The formulas given are for the typical characteristics only at 25°C.

^{6.} Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.



 $^{\star}\text{All}$ unused inputs of AND, NAND gates must be connected to V_{DD}. All unused inputs of OR, NOR gates must be connected to V_{SS}.

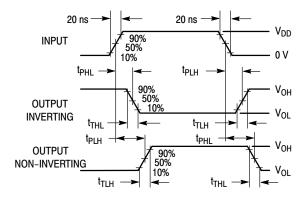
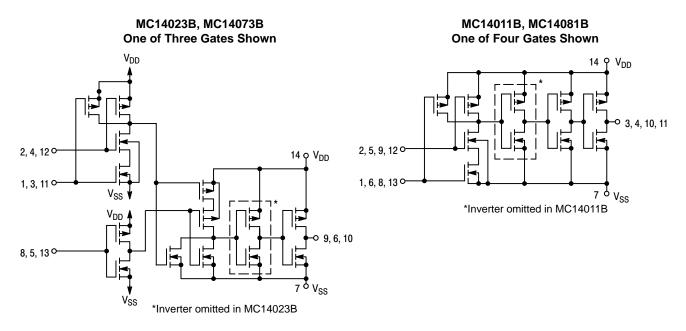


Figure 1. Switching Time Test Circuit and Waveforms

CIRCUIT SCHEMATIC NOR, OR GATES

MC14001B, MC14071B MC14025B One of Three Gates Shown One of Four Gates Shown 14 9 V_{DD} 1, 3, 11 0 1, 6, 8, 13 0-2, 4, 12 0 2, 5, 9, 12 0 14 የ V_{DD} O 3, 4, 10, 11 V_{SS} 0 9, 6, 10 V_{SS} V_{DD} *Inverter omitted in MC14001B 8, 5, 13 0 *Inverter omitted in MC14025B

CIRCUIT SCHEMATIC NAND, AND GATES



TYPICAL B-SERIES GATE CHARACTERISTICS

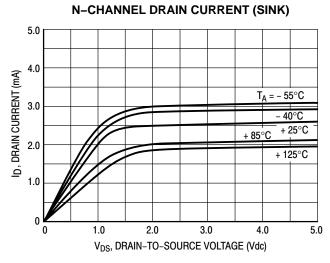


Figure 2. $V_{GS} = 5.0 \text{ Vdc}$

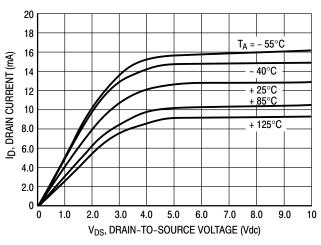


Figure 4. V_{GS} = 10 Vdc

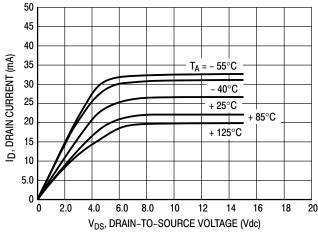


Figure 6. $V_{GS} = 15 \text{ Vdc}$

P-CHANNEL DRAIN CURRENT (SOURCE) - 10 - 9.0 - 8.0 $T_A = -55^{\circ}C$ ID, DRAIN CURRENT (mA) - 7.0 - 6.0 - 5.0 + 25°C - 85°C - 4.0 125°C - 3.0 -2.0- 1.0 - 1.0 - 2.0 - 3.0 - 5.0

Figure 3. $V_{GS} = -5.0 \text{ Vdc}$

V_{DS}, DRAIN-TO-SOURCE VOLTAGE (Vdc)

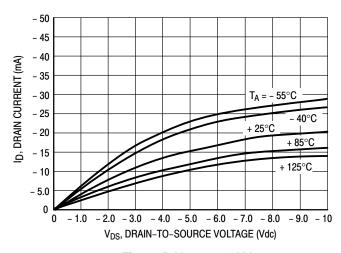


Figure 5. $V_{GS} = -10 \text{ Vdc}$

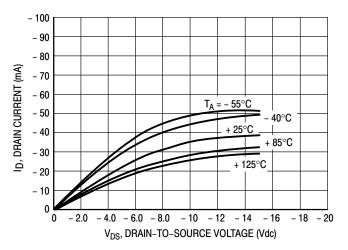


Figure 7. $V_{GS} = -15 \text{ Vdc}$

These typical curves are not guarantees, but are design aids. Caution: The maximum rating for output current is 10 mA per pin.

TYPICAL B-SERIES GATE CHARACTERISTICS (cont'd)

VOLTAGE TRANSFER CHARACTERISTICS

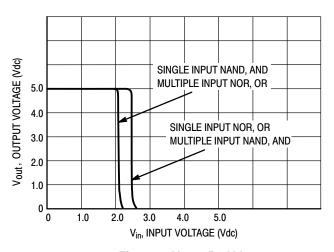


Figure 8. $V_{DD} = 5.0 \text{ Vdc}$

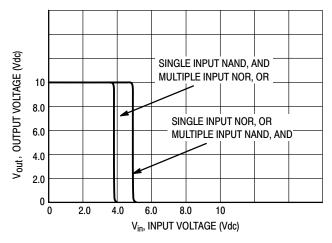


Figure 9. $V_{DD} = 10 \text{ Vdc}$

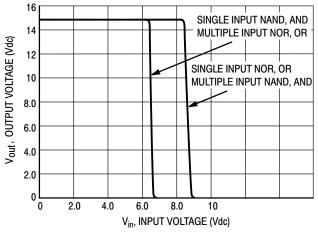


Figure 10. $V_{DD} = 15 \text{ Vdc}$

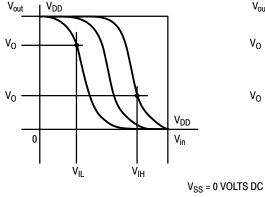
DC NOISE MARGIN

The DC noise margin is defined as the input voltage range from an ideal "1" or "0" input level which does not produce output state change(s). The typical and guaranteed limit values of the input values V_{IL} and V_{IH} for the output(s) to be at a fixed voltage V_O are given in the Electrical Characteristics table. V_{IL} and V_{IH} are presented graphically in Figure 11.

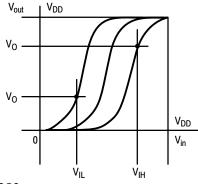
Guaranteed minimum noise margins for both the "1" and "0" levels =

1.0 V with a 5.0 V supply 2.0 V with a 10.0 V supply

2.5 V with a 15.0 V supply



(a) Inverting Function



(b) Non-Inverting Function

Figure 11. DC Noise Immunity

ORDERING INFORMATION

Device	Package	Shipping [†]		
MC14001BCP	PDIP-14	2000 Units / Box		
MC14001BCPG	PDIP-14 (Pb-Free)	2000 Units / Box		
MC14001BD	SOIC-14	2750 Units / Box		
MC14001BDR2	SOIC-14	2500 Units / Tape & Reel		
MC14001BDR2G	SOIC-14 (Pb-Free)	2500 Units / Tape & Reel		
MC14001BDTR2	TSSOP-14*	2500 Units / Tape & Reel		
MC14001BFEL	SOEIAJ-14	2000 Units / Tape & Reel		
MC14001BFELG	SOEIAJ-14 (Pb-Free)	2000 Units / Tape & Reel		
MC14011BCP	PDIP-14	2000 Units / Box		
MC14011BCPG	PDIP-14	2000 Units / Box		
WC14011BCFG	(Pb-Free)	2000 Office / Box		
MC14011BD	SOIC-14	2750 Units / Box		
MC14011BDR2	SOIC-14	2500 Units / Tape & Reel		
MC14011BDR2G	SOIC-14 (Pb-Free)	2500 Units / Tape & Reel		
MC14011BDTR2	TSSOP-14*	2500 Units / Tape & Reel		
MC14011BF	SOEIAJ-14	55 Units / Rail		
MC14011BFEL	SOEIAJ-14	2000 Units / Tape & Reel		
MC14011BFELG	SOEIAJ-14 (Pb-Free)	2000 Units / Tape & Reel		
MC14023BCP	PDIP-14	2000 Units / Box		
MC14023BCPG	PDIP-14 (Pb-Free)	2000 Units / Box		
MC14023BD	SOIC-14	2750 Units / Box		
MC14023BDR2	SOIC-14	2500 Units / Tape & Reel		
MC14023BDR2G	SOIC-14 (Pb-Free)	2500 Units / Tape & Reel		
MC14023BFEL	SOEIAJ-14	2000 Units / Tape & Reel		
MC14025BCP	PDIP-14	2000 Units / Box		
MC14025BCPG	PDIP-14 (Pb-Free)	2000 Units / Box		
MC14025BD	SOIC-14	2750 Units / Box		
MC14025BDR2	SOIC-14	2500 Units / Tape & Reel		
MC14025BDR2G	SOIC-14 (Pb-Free)	2500 Units / Tape & Reel		
MC14025BFEL	SOEIAJ-14	2000 Units / Tape & Reel		

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*This package is inherently Pb–Free.

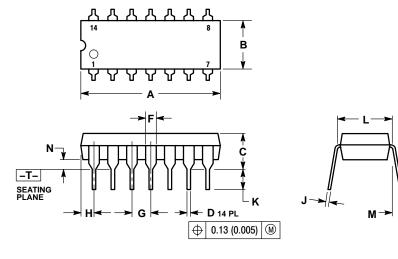
ORDERING INFORMATION

Device	Package	Shipping [†]	
MC14071BCP	PDIP-14	2000 Units / Box	
MC14071BD	SOIC-14	55 Units / Rail	
MC14071BDR2	SOIC-14	2500 Units / Tape & Reel	
MC14071BDR2G	SOIC-14 (Pb-Free)	2500 Units / Tape & Reel	
MC14071BDT	TSSOP-14*	96 Units per Rail	
MC14071BDTR2	TSSOP-14*	2500 Units / Tape & Reel	
MC14071BFEL	SOEIAJ-14	2000 Units / Tape & Reel	
MC14073BCP	PDIP-14	2000 Units / Box	
MC14073BCPG	PDIP-14	2000 Units / Box	
MC14073BCFG	(Pb-Free)	2000 Offits / Box	
MC14073BD	SOIC-14	55 Units / Rail	
MC14073BDG	SOIC-14 (Pb-Free)	55 Units / Rail	
MC14073BDR2	SOIC-14	2500 Units / Tape & Reel	
MC14073BDR2G	SOIC-14 (Pb-Free)	2500 Units / Tape & Reel	
MC14073BFEL	SOEIAJ-14	2000 Units / Tape & Reel	
MC14081BCP	PDIP-14	2000 Units / Box	
MC14081BCPG	PDIP-14 (Pb-Free)	2000 Units / Box	
MC14081BD	SOIC-14	55 Units / Rail	
MC14081BDG	SOIC-14 (Pb-Free)	55 Units / Rail	
MC14081BDR2	SOIC-14	2500 Units / Tape & Reel	
MC14081BDR2G	SOIC-14 (Pb-Free)	2500 Units / Tape & Reel	
MC14081BDTR2	TSSOP-14*	2500 Units / Tape & Reel	
MC14081BFEL	SOEIAJ-14	2000 Units / Tape & Reel	
MC14081BFELG	SOEIAJ-14 (Pb-Free)	2000 Units / Tape & Reel	
	•		
MC14082BCP	PDIP-14	2000 Units / Box	
MC14082BCPG	PDIP-14 (Pb-Free)	2000 Units / Box	
MC14082BD	SOIC-14	55 Units / Rail	
MC14082BDG	SOIC-14 (Pb-Free)	55 Units / Rail	
MC14082BDR2	SOIC-14	2500 Units / Tape & Reel	
MC14082BDR2G	SOIC-14 (Pb-Free)	2500 Units / Tape & Reel	
		nlease refer to our Tane and Reel Packaging	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*This package is inherently Pb–Free.

PACKAGE DIMENSIONS

P SUFFIX PLASTIC DIP PACKAGE CASE 646-06 ISSUE N



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING
 PER ANSI Y14.5M, 1982.

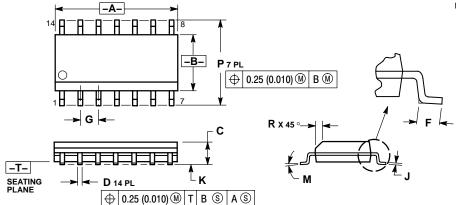
 2. CONTROLLING DIMENSION: INCH.

 3. DIMENSION L TO CENTER OF LEADS
 WHEN FORMED PARALLEL.
- 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIM	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.715	0.770	18.16	18.80
В	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100	BSC	2.54 BSC	
Н	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.290	0.310	7.37	7.87
М		10 °		10 °
N	0.015	0.039	0.38	1.01

D SUFFIX PLASTIC SOIC PACKAGE CASE 751A-03 **ISSUE G**



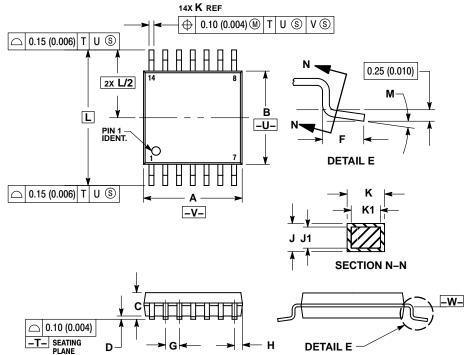
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE
- PER SIDE.

 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE
 DAMBAR PROTRUSION SHALL BE 0.127 0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	8.55	8.75	0.337	0.344
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0 °	7°	0 °	7°
Р	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

PACKAGE DIMENSIONS

DT SUFFIX PLASTIC TSSOP PACKAGE CASE 948G-01 **ISSUE O**



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION ALLOWABLE DAMBAR PROTRUSION SHALL BOMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION. CONDITION.

 6. TERMINAL NUMBERS ARE SHOWN FOR

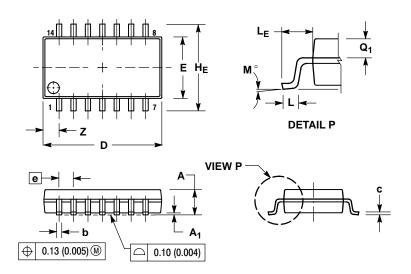
 - REFERENCE ONLY.

 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026 BSC	
Н	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252	BSC
М	0 °	8°	0°	8 °

PACKAGE DIMENSIONS

F SUFFIX PLASTIC EIAJ SOIC PACKAGE CASE 965-01 **ISSUE O**



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2 CONTROLLING DIMENSION: MILLIMETER.
 3 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- PER SIDE.
 TERMINAL NUMBERS ARE SHOWN FOR
 REFERENCE ONLY.
 THE LEAD WIDTH DIMENSION (b) DOES NOT
 INCLUDE DAMBAR PROTRUSION. ALLOWABLE
 DAMBAR PROTRUSION SHALL BE 0.08 (0.003) DANIBATT HOTTOGON STRALE DE USB (USBO)
 TOTAL IN EXCESS OF THE LEAD WIDTH
 DIMENSION AT MAXIMUM MATERIAL CONDITION.
 DAMBAR CANNOT BE LOCATED ON THE LOWER
 RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05	-	0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050	BSC
HE	7.40	8.20	0.291	0.323
0.50	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10 °	0°	10°
Q_1	0.70	0.90	0.028	0.035
Z		1.42		0.056

ON Semiconductor and was are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its partnif rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 61312, Phoenix, Arizona 85082-1312 USA Phone: 480-829-7710 or 800-344-3860 Toll Free USA/Canada Fax: 480-829-7709 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free

Japan: ON Semiconductor, Japan Customer Focus Center 2-9-1 Kamimeguro, Meguro-ku, Tokyo, Japan 153-0051 Phone: 81-3-5773-3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative.

This datasheet has been download from:

www.datasheetcatalog.com

Datasheets for electronics components.